

Method of assembly of capacitive biosensor for bio-molecules detection

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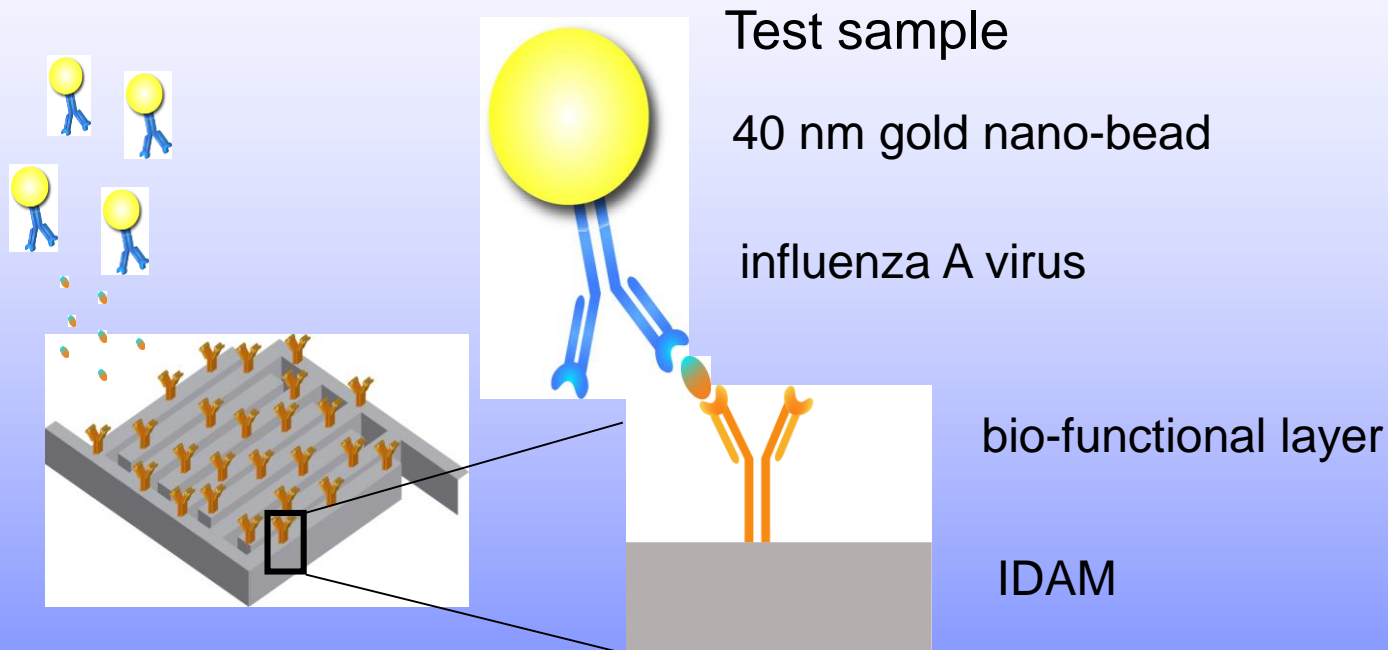
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Overview

- Introduction
- Sensor construction
- Bio-functionalization
- Assembly process flow
- Electrical characterization
- Conclusions

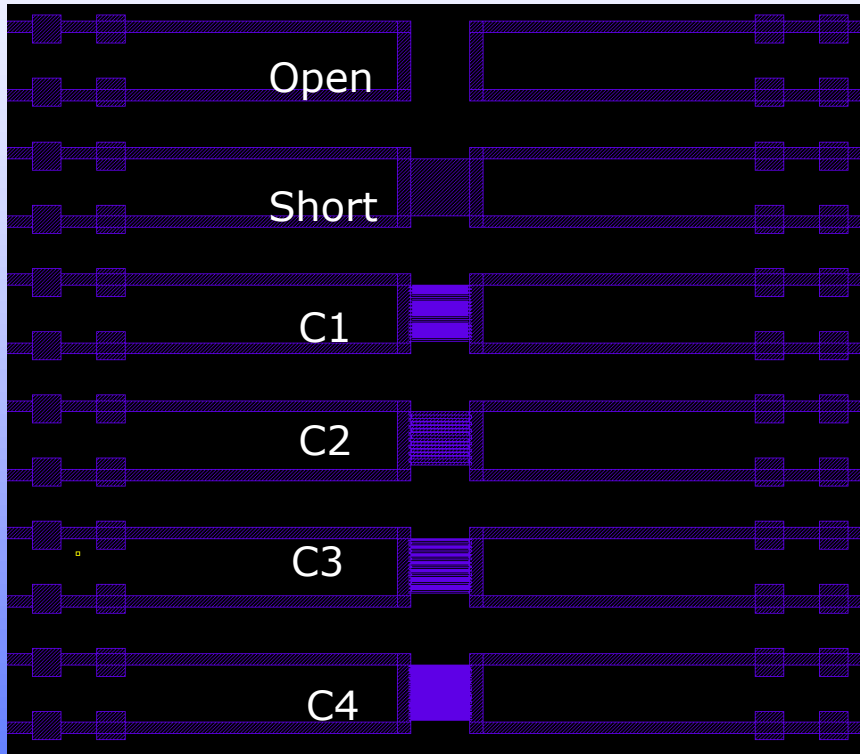
Principe of detection



The inter-digitated array microelectrodes (IDAM) is covered with a bio-functional layer (specific antibody recognizing the nucleoprotein of the Influenza A virus). The registered response is variation of the capacitance and conductivity between the IDAM. To increase the signal a 40 nm gold nano-bead are conjugated with influenza A virus.

Sensor die

Sensor die layout (top view)

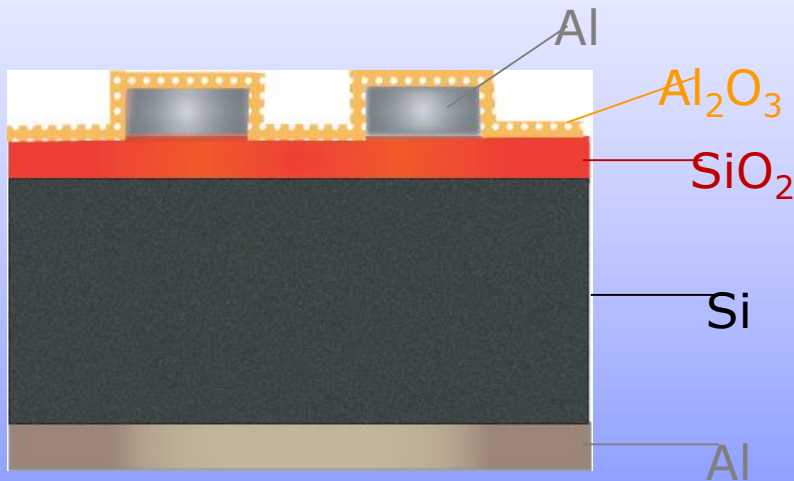


Sensing areas (C1...C4) configuration

Sensor	Finger width (μm)	Interspace (μm)
C1	2	4
C2	10	2
C3	5	2
C4	2	2

Si sensor die of 3.2mmx3.2mm with 4 of 200μmx200μm sensing areas (C1...C4) of different configuration IDAM (inter-digitated array microelectrodes)

Sensor die cross sectional view



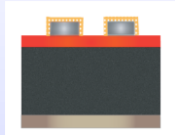
Al=800nm


SiO₂=50nm

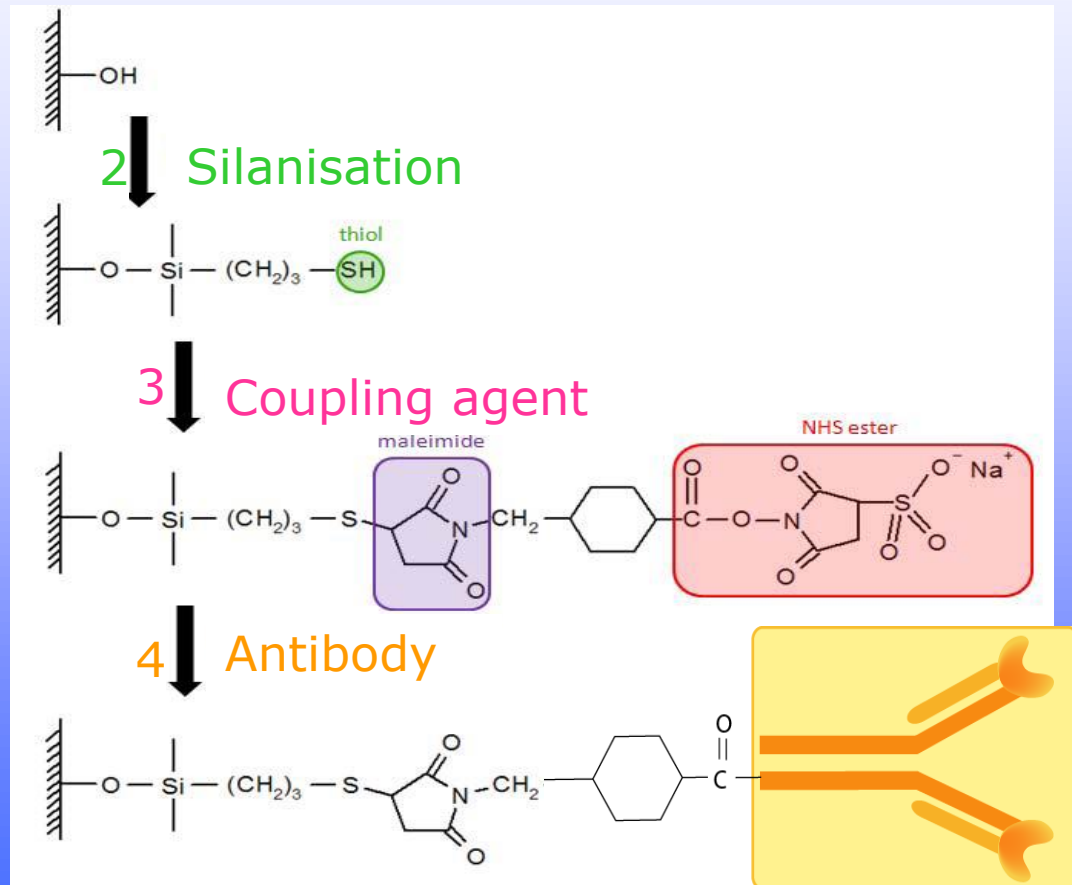
Si wafer=600μm

Al=400nm

Bio-functionalization



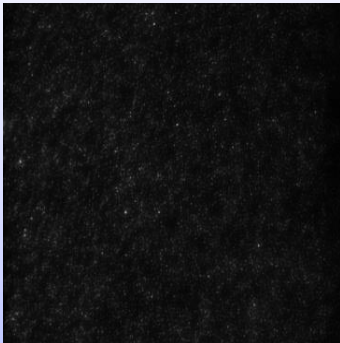
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 Plasma/O₂ treatment



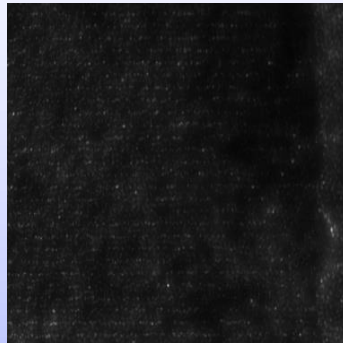
Surface analyses (confocal microscopy)

Prior to bio-functionalization

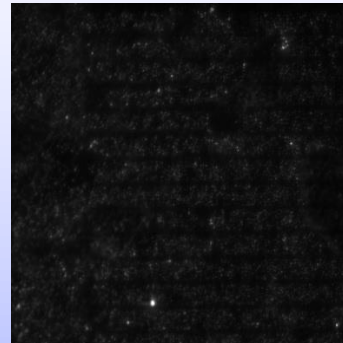
Short



C1



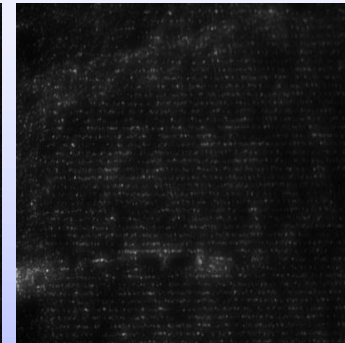
C2



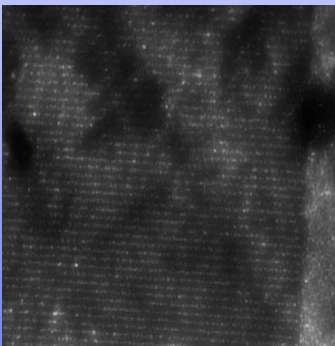
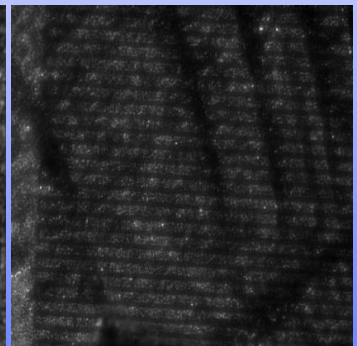
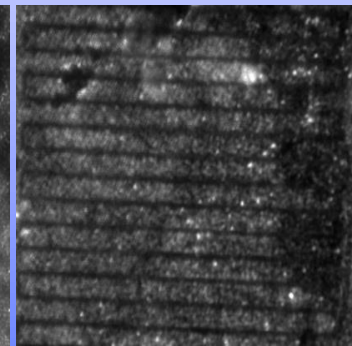
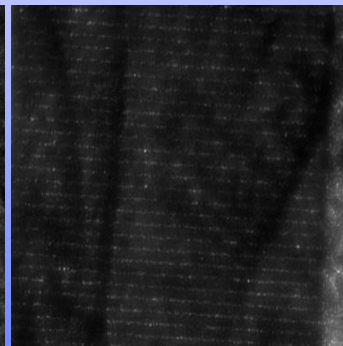
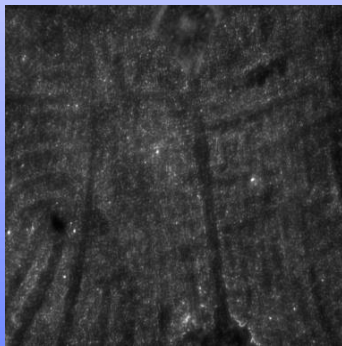
C3



C4

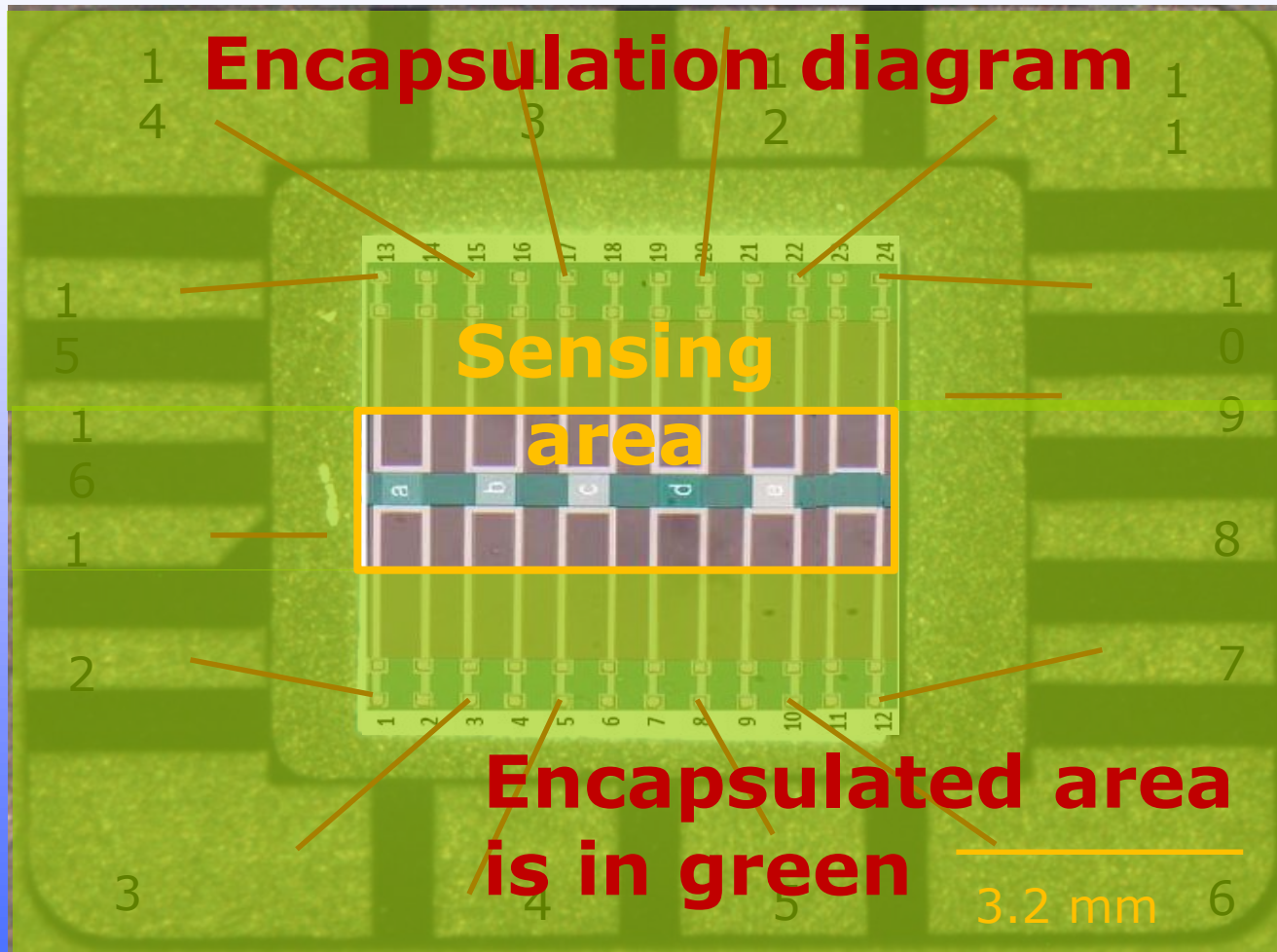


+ Fluorescent Ab



Confirmation by confocal microscopy of the engraftment of the capture antibody: the signal of the fluorescent marker was observed on every functionalized structure of the chip while a weak fluorescence was distinguishable on the non-functionalized chip.

Assembly schematic view



Sensing channel (configuration of 1mm width x 3 mm length and 0.5 mm high) is to doze 1-1.5 ml volume of the test sample.

Assembly process flow

- Die attach (mounting the sensor die in the package)
- Wire bonding (electrical connection between the sensor die and the package)
- Encapsulation:
 - Protect the bond pad on the sensor die
 - Protect the wire
 - Protect the lead (bond pad) on the package
 - Define the sensing area

Assembly process challenges

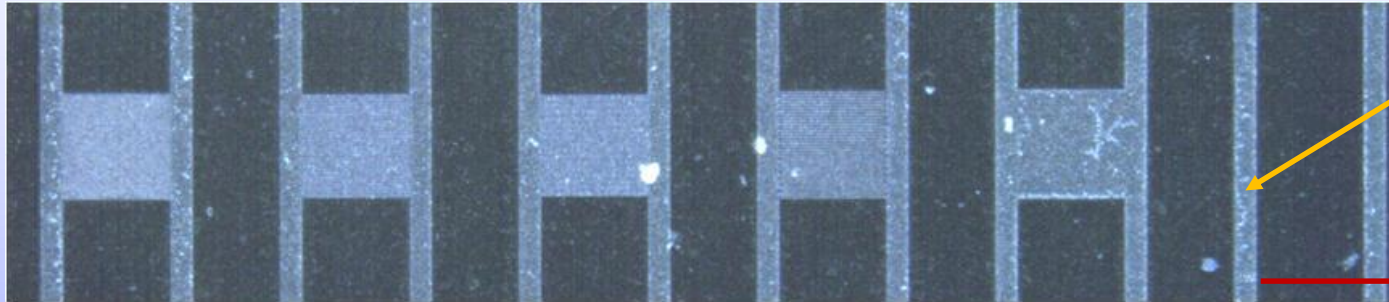
- Die attach:
 - Die pick and place normally required a direct top contact on the die
 - Permanent die fixation usually performed at elevated temperature ($>40^{\circ}\text{C}$, typically 150°C)
- Wire bonding: standard technology requires elevated temperature ($>40^{\circ}\text{C}$, typically 150°C)
- Encapsulation: standard technology requires elevated temperature ($>40^{\circ}\text{C}$, typically 150°C)

Die mounting

- Pick and place without direct contact with sensing area (no damage to the bio-functionalized layer, no damage to vulnerable IDAM)
- Permanent fixation is achieved at room temperature

Sensing area observation

As received



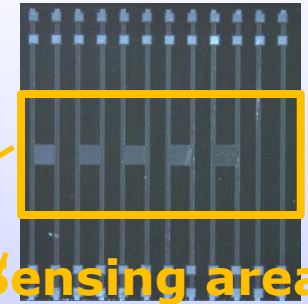
200 μm

After encapsulation



200 μm

No visual damage induced during the assembly flow

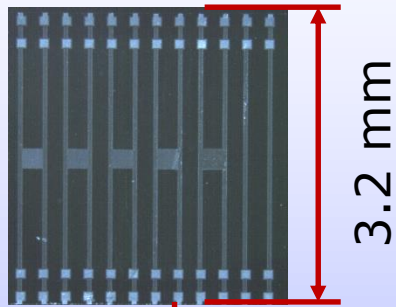


Sensing area

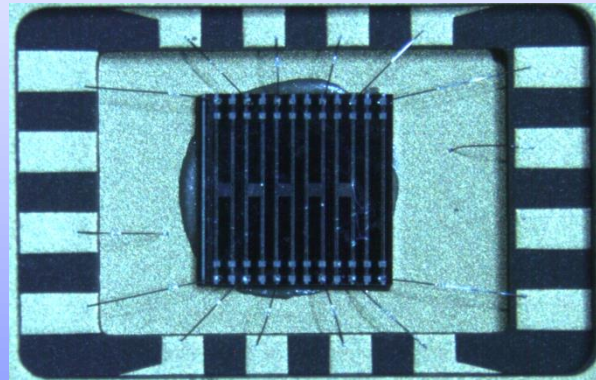
Wire bonding

- Industrial standard is Au wire bonding. Cu wire bonding emerges. In total they count for 90%. They require elevated temperature (typically 150-220°C)
- We interconnect the sensor die using Al wire bonding (room temperature process)
- Al wire bonding is currently used for special applications (military, space etc)

Process flow

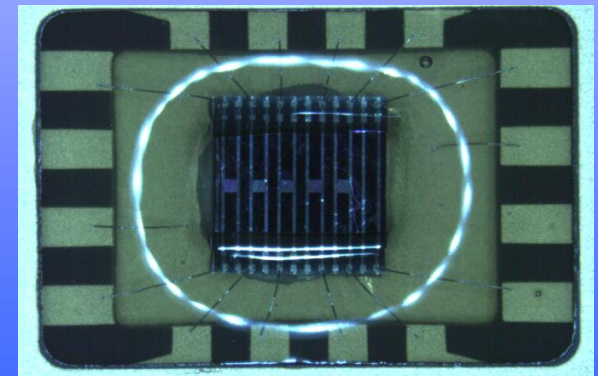


"As received sensor die (after bio-functionalization)

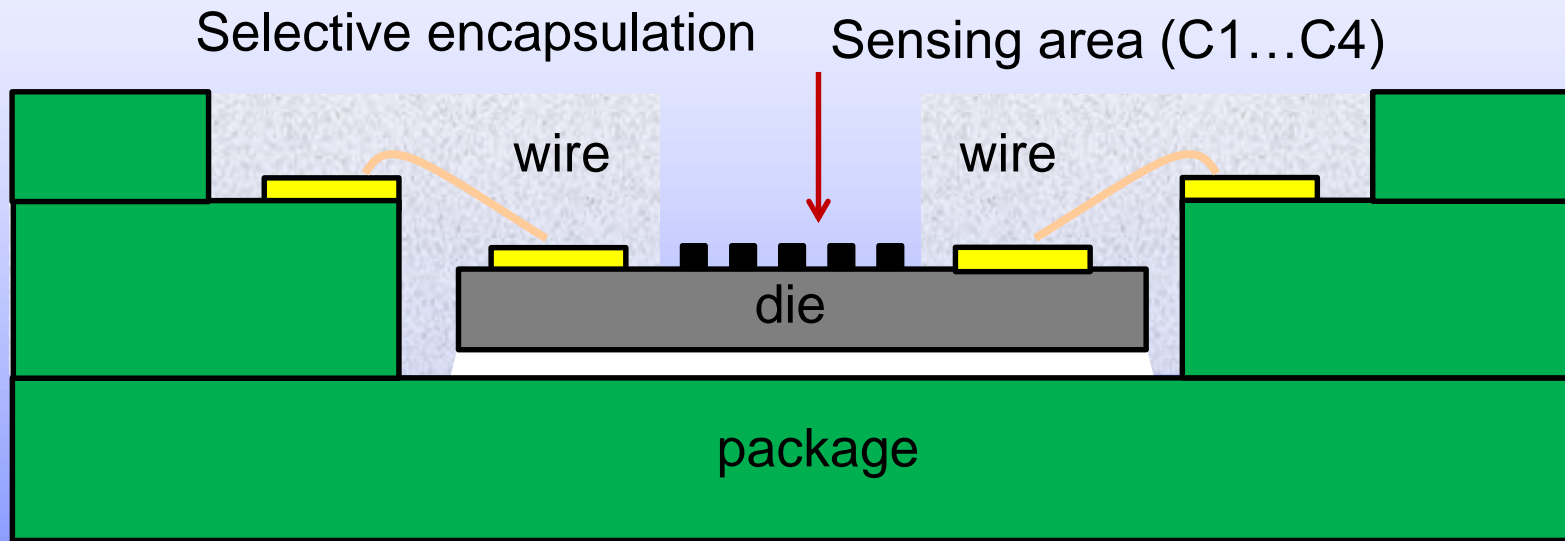


Sensor die mounted into package and wire bonded

Encapsulated sensor die (transparent encapsulant)



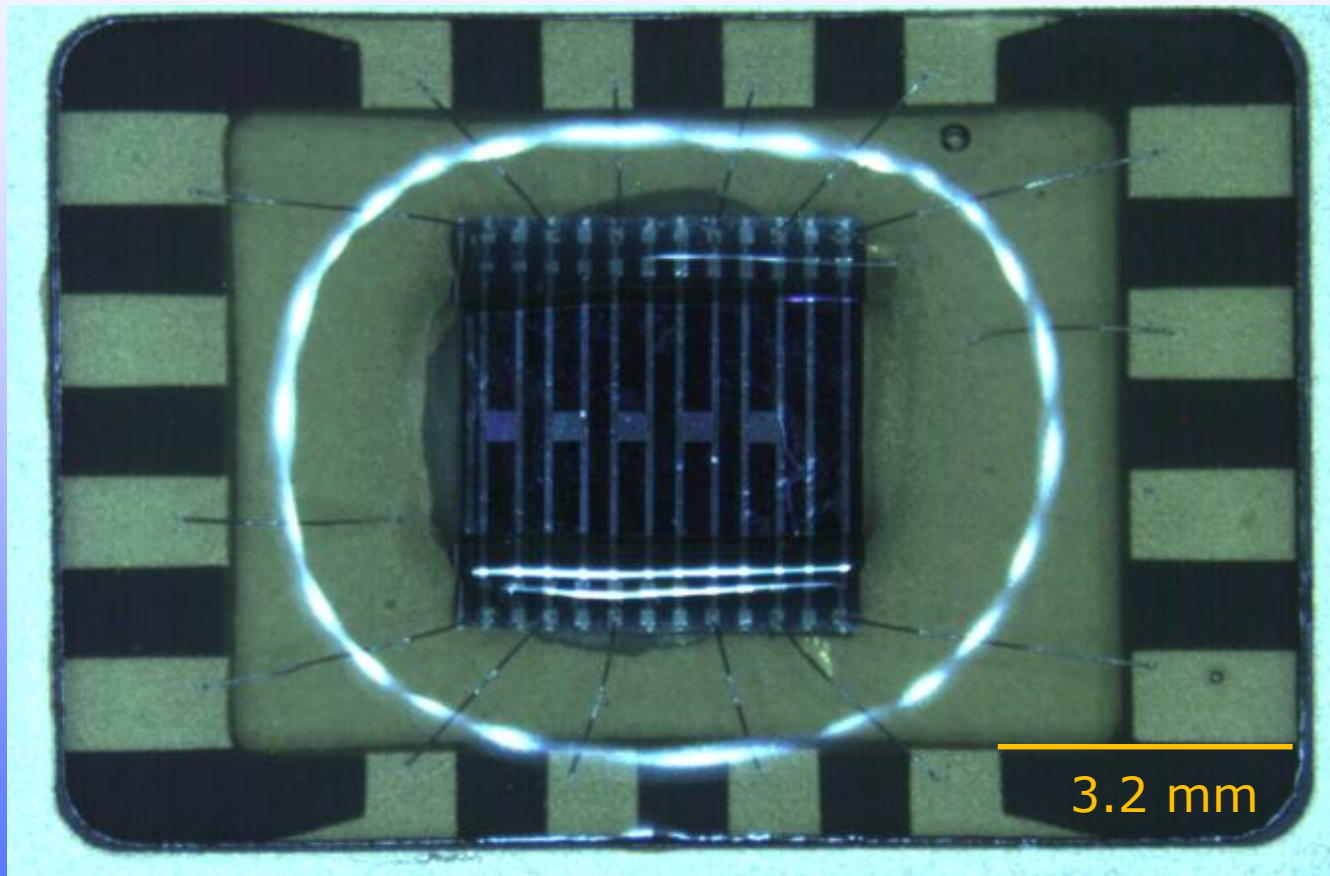
Assembled sensor: cross sectional view



Encapsulation challenges

- Partial encapsulation to define accurately the sensing area (1mm x 3 mm and 0.5 mm high):
 - dam (high viscosity) and encapsulant (lower viscosity)
 - Industrial process: partial molding
- UV curable encapsulant (UV spot intensity: 18.5W/cm² irradiance maximum output, wave length of 320-500nm), maximum 20 sec
- Such UV exposure causing no direct damage to bio-functionalized layer of the sensor (tested experimentally)

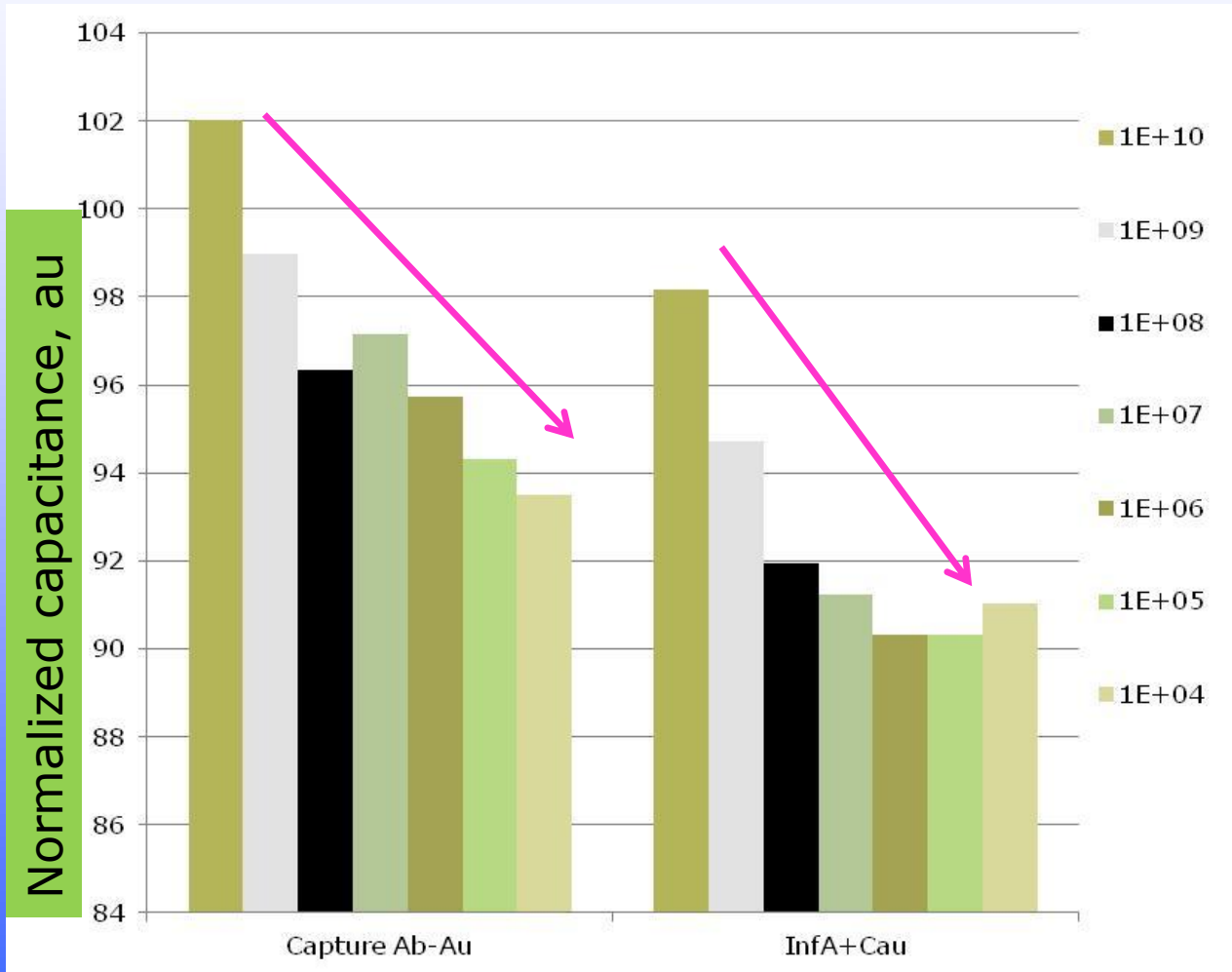
Assembled sensor (top view)



Electrical characterization

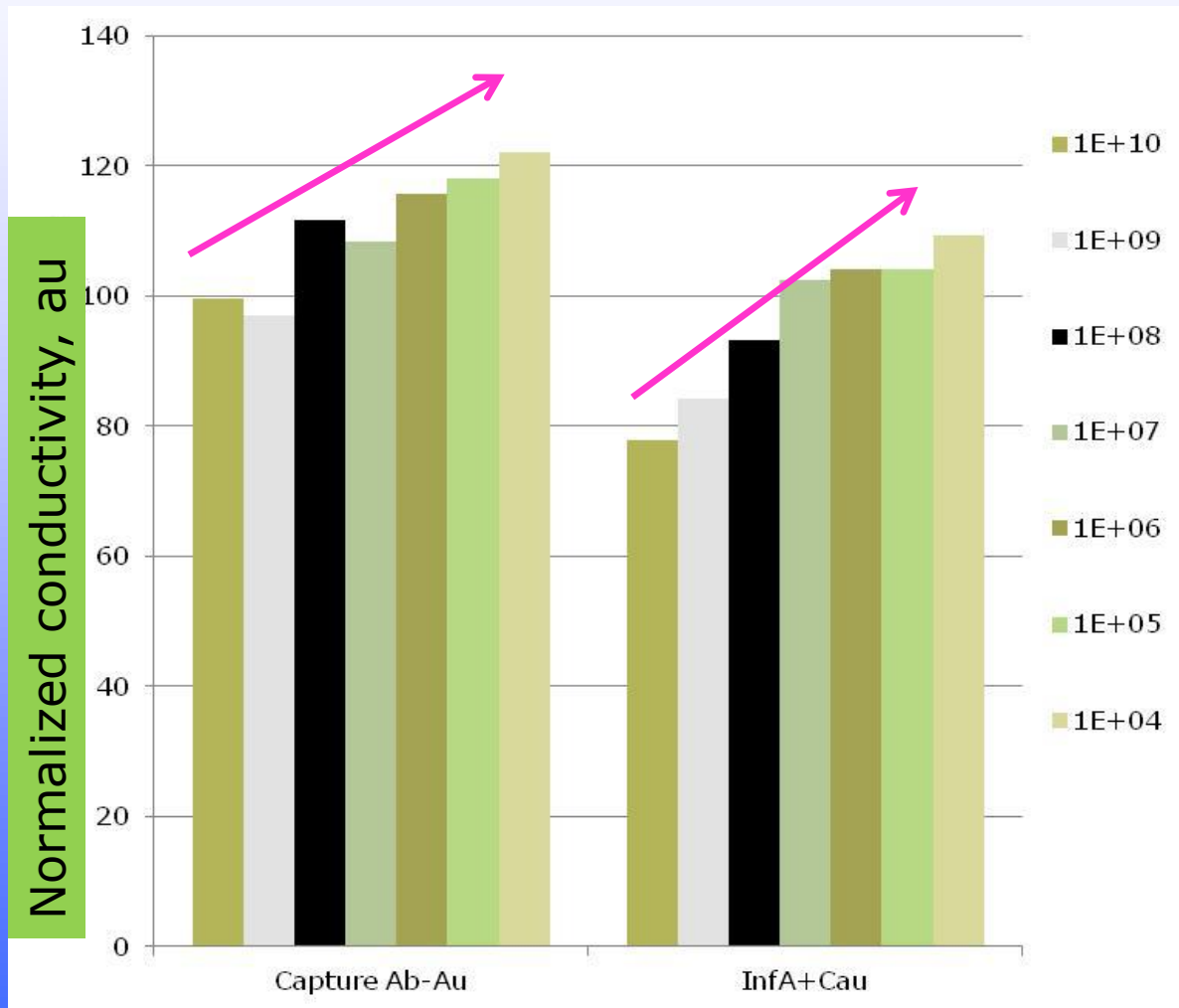
- Capacitance and conductivity measurements (PO_4 buffer; 20 mM, pH 8)(freq=100 kHz): the measurements were performed with a LCR meter with different bias voltages. Different dilutions of (left) antibody conjugated with gold bead, in contact with antibodies (initial concentration= 10^{13} beads/mL) or (right) different dilutions of the Influenza A virus were tested.
- For the measurements of the Influenza A virus, the signal was enhanced with an anti-Influenza antibody conjugated with a gold nano-bead. The same trend was observed for both targets.

Capacitance



Ab-Au:
antibody
conjugated with
gold nano-bead
InfA+Cau:
Influenza A virus
enhanced with an
anti-Influenza
antibody
conjugated with a
gold nano-bead

Conductivity



Ab-Au:
antibody conjugated with gold nano-bead

InfA+Cau:
Influenza A virus enhanced with an anti-Influenza antibody conjugated with a gold nano-bead

Sensor performance summary

- We demonstrated inter-digitated capacitive biosensor can be used for the quantification of the Influenza A virus
- The demonstrated sensor can detect to 10^{10} times dilution of the Influenza A virus while a commercial immunochromatographic test could only detect a 10^4 times dilution
- We successfully developed a process for applying bio-functional layer on IDAM. The layer is suitable for conjugating specific antibody and Influenza A virus
- The capacitance and conductance measurements are coherent with the test sample concentration
- Among all tested sensors (C1...C4), the C4 ($2 \mu\text{m}/2 \mu\text{m} =$ line/space) is the most sensitive one.

Conclusion

- We developed a convenient method for the assembly of the bio-functionalized sensor
- The process temperature is below 37°C; there is no direct contact between the die handling tool and the bio-functionalized area of the bio-sensor
- Additionally, the UV exposure, specifically intensity and time are limited to a sustainable level for inducing no damage to the bio-sensor
- The realized sensor performs detection and semi-quantification of influenza A viruses.

Acknowledgement

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Questions

Thanks for your attention:

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